



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Sun, et al.

Serial No.: 10/616,097

Confirmation No.: 1645

Filed: July 8, 2003

For: Multiple-Step
Electrodeposition Process
for Direct Copper Plating
on Barrier Metals

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Group Art Unit: 1753

Examiner: Edna Wong

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on
September 8, 2005 with the United States Postal Service as
First Class Mail in an envelope addressed to: Commissioner
for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 8, 2005
Date

[Signature]
Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED JUNE 8, 2005

In response to the Office Action dated June 8, 2005, having a shortened statutory period for response set to expire on September 8, 2005, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims begin on page 2 of this paper. **Remarks** begin on page 8 of this paper.